

positioning at least one of said plurality of electrodes to oppose at least one of said plurality of leads; and

applying pressure in a direction such as to make a gap between said semiconductor chip and said substrate narrower;

wherein on the surface of said substrate on which said leads are formed, in a region being at least part of a region of adherence of said semiconductor chip, a film is formed with a lower adhesion to said adhesive than a base material of said substrate, and said film is broader than each of said leads at their portions opposed to said electrodes.

12. (Twice Amended) A semiconductor device comprising:

a semiconductor chip having a plurality of electrodes;

a substrate on which is formed a plurality of leads; and

an adhesive provided between a surface of said semiconductor chip on which said electrodes are formed and a surface of said substrate on which said leads are formed, and adhering said semiconductor chip and said substrate,

wherein at least one of said plurality of electrodes and at least one of said plurality of leads are electrically connected; and

wherein on said substrate in a region including at least a part of a region opposing said semiconductor chip, a film is formed with a lower adhesion to said adhesive than a base material of said substrate, and said film is broader than each of said leads at their portions opposed to said electrodes.

REMARKS

Claims 1-10, 12-19 and 21-22 are pending. By this amendment, claims 1 and 12 are amended. Reconsideration based on the above amendments and following remarks is respectfully requested.